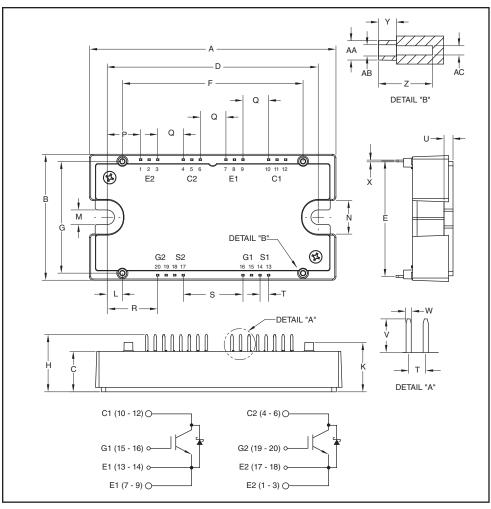


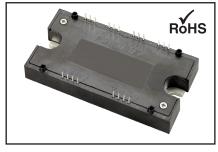
### Split Dual Si/SiC Hybrid IGBT Module 100 Amperes/1200 Volts



### **Outline Drawing and Circuit Diagram**

Dimensions	Inches	Millimeters	
Α	4.32	109.8	
В	2.21	56.1	
С	0.71 18.0		
D	3.70±0.02 94.0±0.5		
E	2.026	51.46	
F	3.17	80.5	
G	1.96	49.8	
Н	1.00	25.5	
K	0.87	22.0	
L	0.266	6.75	
М	0.26	6.5	
N	0.59	15.0	
Р	0.586	14.89	

Dimensions	Inches	Millimeters
Q	0.449	11.40
R	0.885	22.49
S	1.047	26.6
Т	0.15	3.80
U	0.16	4.0
V	0.30	7.5
W	0.045	1.15
Χ	0.03	0.8
Υ	0.16	4.0
Z	0.47	12.1
AA	0.17 Dia. 4.3 Dia	
AB	0.10 Dia.	2.5 Dia.
AC	0.08 Dia.	2.1 Dia.



### **Description:**

Powerex IGBT Modules are designed for use in high frequency applications; upwards of 30 kHz for hard switching applications and 80 kHz for soft switching applications. Each module consists of two IGBT Transistors with each transistor having a reverse-connected super-fast recovery free-wheel silicon carbide Schottky diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

### Features:

- ☐ Low EsW(off)
- □ Aluminum Nitride Isolation
- □ Discrete Super-Fast Recovery Free-Wheel Silicon Carbide Schottky Diode
- □ Low Internal Inductance
- ☐ 2 Individual Switches per Module
- ☐ Isolated Baseplate for Easy Heat Sinking
- □ Copper Baseplate
- □ RoHS Compliant

### **Applications:**

- Energy Saving PowerSystems such as:Fans; Pumps; Consumer
  - Fans; Pumps; Consumer Appliances
- ☐ High Frequency Type Power
  Systems such as:

  LIPS: High Speed Motor Prive
  - UPS; High Speed Motor Drives; Induction Heating; Welder; Robotics
- ☐ High Temperature Power
  Systems such as:
  Power Electronics in Electric
  Vehicle and Aviation Systems



QID1210007 Split Dual Si/SiC Hybrid IGBT Module 100 Amperes/1200 Volts

### Absolute Maximum Ratings, $T_j = 25^{\circ}\text{C}$ unless otherwise specified

Ratings	Symbol	QID1210007	Units
Junction Temperature	Тј	-40 to 150	°C
Storage Temperature	T <sub>stg</sub>	-40 to 150	°C
Collector-Emitter Voltage (G-E Short)	VCES	1200	Volts
Gate-Emitter Voltage (C-E Short)	V <sub>GES</sub>	±20	Volts
Collector Current (T <sub>C</sub> = 25°C)	IC	100*	Amperes
Peak Collector Current	ICM	200*	Amperes
Emitter Current** (T <sub>C</sub> = 25°C)	lΕ	75*	Amperes
Repetitive Peak Emitter Current (T <sub>C</sub> = 25°C)**	IEM	150 *	Amperes
Maximum Collector Dissipation ( $T_C = 25^{\circ}C, T_j \le 150^{\circ}C$ )	PC	730	Watts
Mounting Torque, M6 Mounting	_	40	in-lb
Weight	_	270	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	V <sub>ISO</sub>	2500	Volts

### IGBT Electrical Characteristics, $T_j = 25$ °C unless otherwise specified

Characteristics		Symbol	Test Conditions	Min.	Тур.	Max.	Units
Collector-Cutof	f Current	ICES	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0V	_	_	1.0	mA
Gate Leakage	Current	IGES	V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0V	_	_	0.5	μΑ
Gate-Emitter Th	hreshold Voltage	VGE(th)	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10V	4.5	6.0	7.5	Volts
Collector-Emitter Saturation Voltage		VCE(sat)	I <sub>C</sub> = 100A, V <sub>GE</sub> = 15V, T <sub>j</sub> = 25°C	_	5.0	6.5	Volts
			I <sub>C</sub> = 100A, V <sub>GE</sub> = 15V, T <sub>j</sub> = 125°C	_	5.0	_	Volts
Total Gate Cha	rge	QG	V <sub>CC</sub> = 600V, I <sub>C</sub> = 100A, V <sub>GE</sub> = 15V	_	450	_	nC
Input Capacitar	nce	C <sub>ies</sub>		_	_	16	nf
Output Capacit	ance	C <sub>oes</sub>	$V_{CE} = 10V, V_{GE} = 0V$	_	_	1.3	nf
Reverse Transf	er Capacitance	C <sub>res</sub>	_	_	_	0.3	nf
Inductive	Turn-on Delay Time	<sup>t</sup> d(on)	$V_{CC} = 600V, I_{C} = 100A,$	_	_	TBD	ns
Load	Rise Time	t <sub>r</sub>	$V_{GE1} = V_{GE2} = 15V,$	_	_	TBD	ns
Switch	Turn-off Delay Time	t <sub>d</sub> (off)	$R_G = 3.1\Omega$ ,	_	_	TBD	ns
	TimeFall Time	tf	Inductive Load Switching Operation	_	_	TBD	ns

<sup>\*</sup> Pulse width and repetition rate should be such that device junction temperature (Tj) does not exceed Tj(max) rating. \*\*Represents characteristics of the anti-parallel, emitter-to-collector silicon carbide Schottky diode (FWDi).



QID1210007 Split Dual Si/SiC Hybrid IGBT Module 100 Amperes/1200 Volts

### Reverse Schottky Diode Characteristics, $T_{j}$ = 25 °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Diode Forward Voltage	VFM	IF = 75A, VGE = -5V	_	1.45	1.75	Volts
		$I_F = 75A$ , $V_{GE} = -5V$ , $T_j = 175$ °C	_	1.95	2.35	Volts
Diode Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 1200V	_	0.9	5.0	mA
		V <sub>R</sub> = 1200, T <sub>j</sub> = 175°C	_	6.0	33.3	mA
Diode Capacitive Charge	QC	V <sub>R</sub> = 1200V, I <sub>F</sub> = 75A, di/dt = 1100A/μs	_	300	_	nC

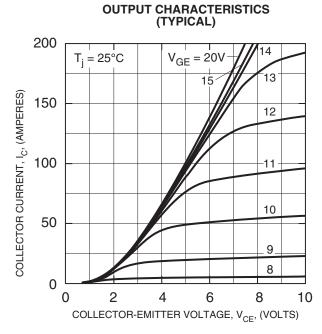
### Thermal and Mechanical Characteristics, T<sub>i</sub> = 25 °C unless otherwise specified

		<del>-</del>				
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	R <sub>th(j-c)</sub> Q	Per IGBT 1/2 Module,	_	_	0.17	°C/W
		T <sub>C</sub> Reference Point Under Chips				
Thermal Resistance, Junction to Case	R <sub>th(j-c)</sub> D	Per FWDi 1/2 Module, T <sub>C</sub> Reference	_	_	0.50	°C/W
		T <sub>C</sub> Reference Point Under Chips				
Contact Thermal Resistance	Rth(c-f)	Per 1/2 Module, Thermal Grease Applied	_	0.04	_	°C/W
External Gate Resistance	RG		3.1	_	31	Ω
Internal Inductance	L <sub>int</sub>	IGBT Part	_	10	_	nH

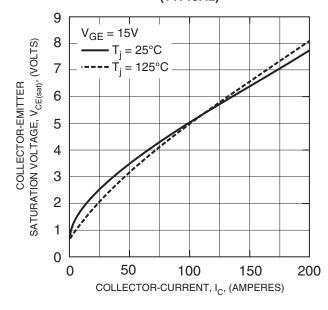


### QID1210007 Split Dual Si/SiC Hybrid IGBT Module 100 Amperes/1200 Volts

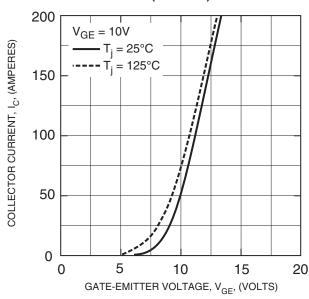
### OUTDUT CHADACTEDISTICS



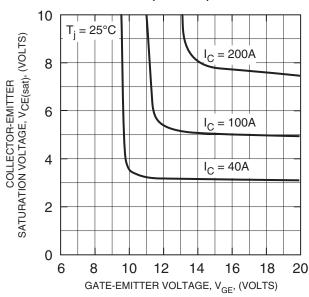
# COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



### TRANSFER CHARACTERISTICS (TYPICAL)



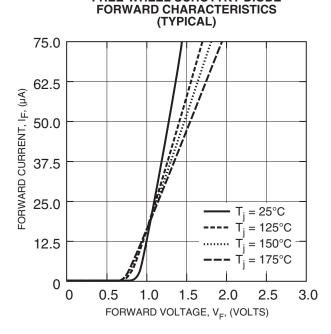
# COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)

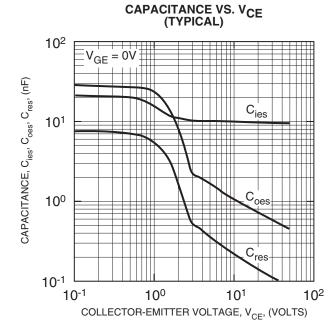




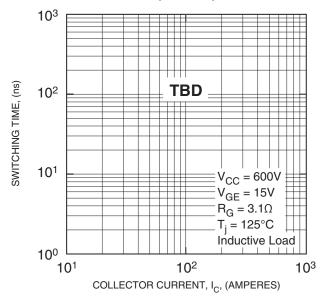
### QID1210007 Split Dual Si/SiC Hybrid IGBT Module 100 Amperes/1200 Volts

# FREE-WHEEL SCHOTTKY DIODE

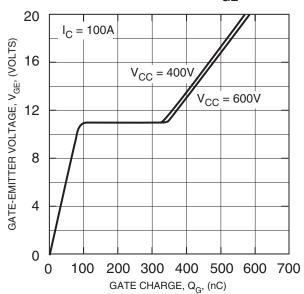




#### HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)



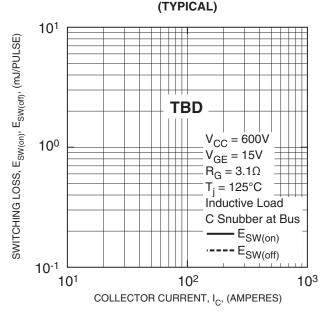
### GATE CHARGE VS. VGF



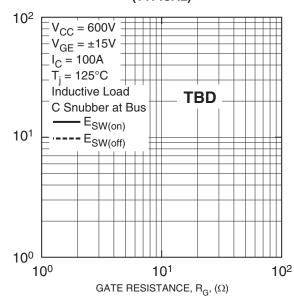


### QID1210007 Split Dual Si/SiC Hybrid IGBT Module 100 Amperes/1200 Volts

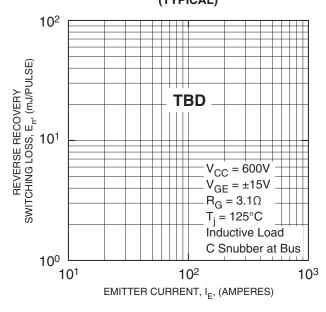




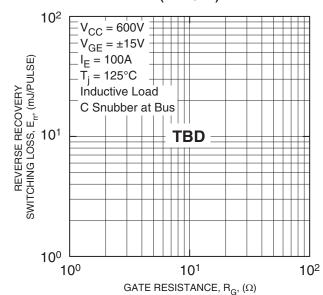
#### SWITCHING LOSS VS. GATE RESISTANCE (TYPICAL)



# REVERSE RECOVERY SWITCHING LOSS VS. EMITTER CURRENT (TYPICAL)



## REVERSE RECOVERY SWITCHING LOSS VS. GATE RESISTANCE (TYPICAL)



 ${\rm SWITCHING\ LOSS,\ E_{\rm SW(on)},\ E_{\rm SW(off)},\ (mJ/PULSE)}$ 



### QID1210007 Split Dual Si/SiC Hybrid IGBT Module 100 Amperes/1200 Volts

